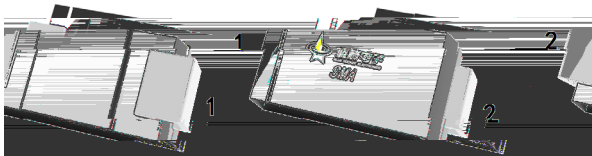


0



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size

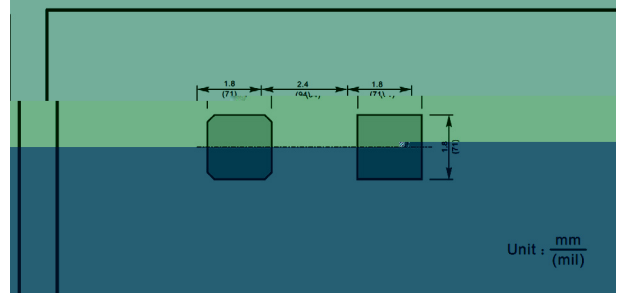




Fig.1 Forward Current Derating Curve

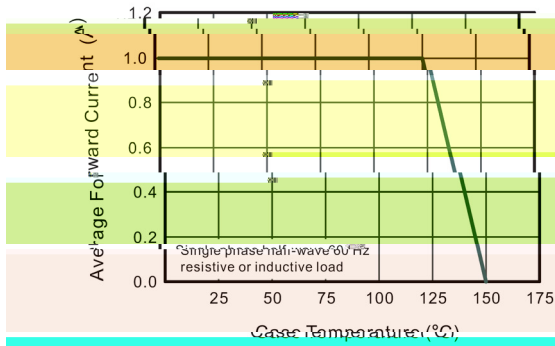


Fig.2 Typical Reverse Characteristics

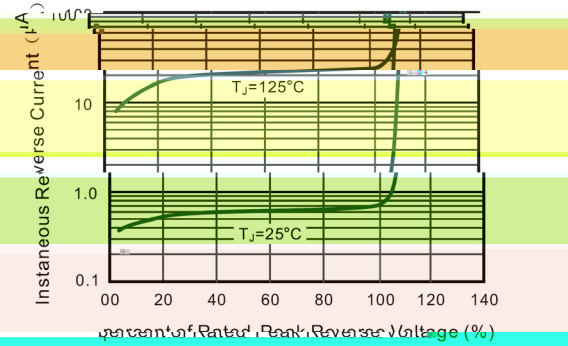


Fig.3 Typical Forward Characteristics

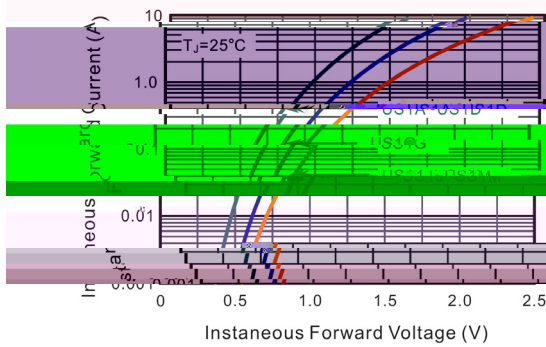


Fig.4 Maximum Non-Repetitive Peak Forward Surge Current

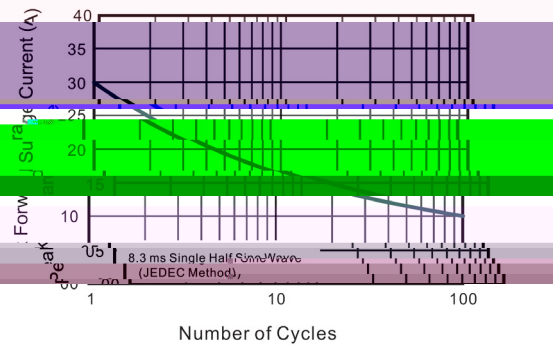


Fig.5- Typical Transient Thermal Impedance

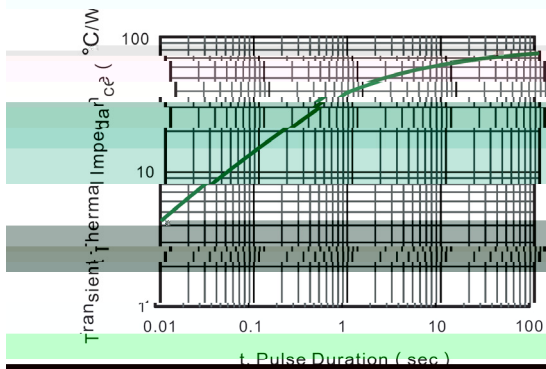
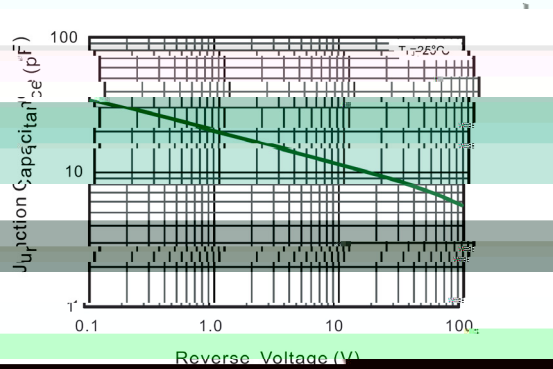
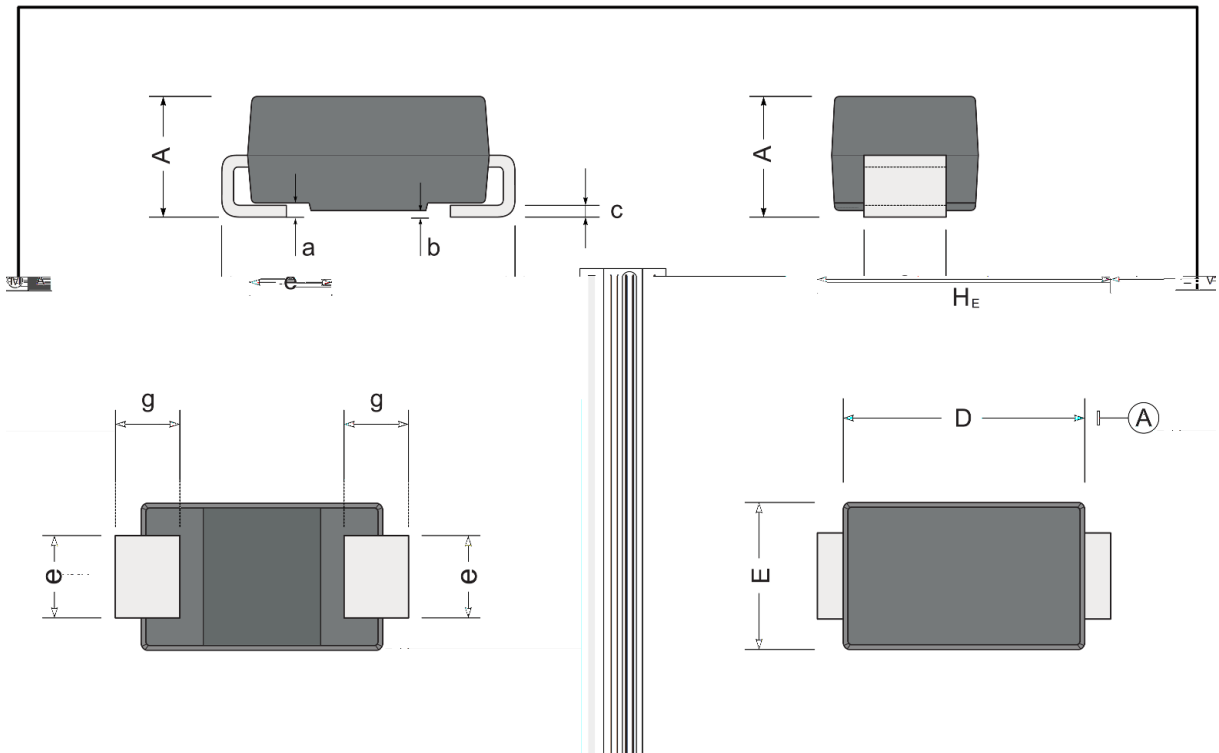


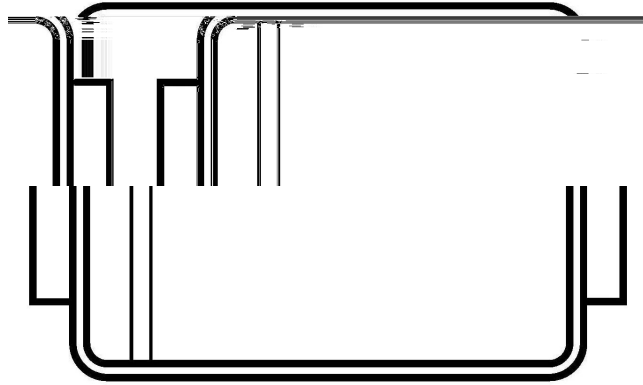
Fig.6 Typical Junction Capacitance



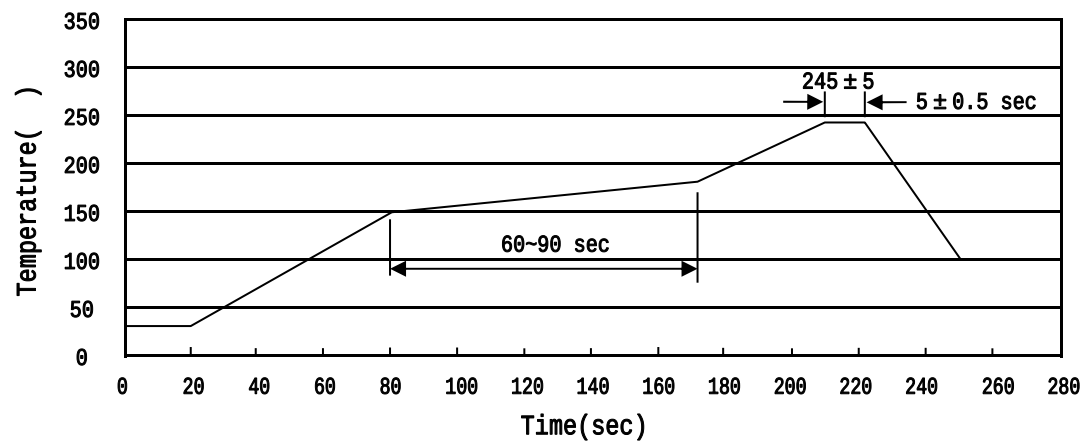
SMA



	c	e	g	b	a						
2	0.31	1.6	1.5	0.2	0.3	UNIT	A	D	E	H _E	
7	0.15	1.3	0.9	0.05		mm	max	2.2	4.5	2.7	5.2
							min	1.9	4.0	2.3	4.7
035	12.5	63.2	58.7	7.0		mil	max	57.25	181	106	
185	6	5	35	2			min	75	157	92	

[illegible]

Temperature Profile for IR Reflow Soldering(Pb-Free)



	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box